

CLAIM AMENDMENTS

IN THE CLAIMS

This listing of the claims will replace all prior versions, and listing, of claims in the application or previous response to office action:

1. (Original) Circuit arrangement with semiconductor elements arranged in chips comprising:

- at least one metallic body for electrical contacting of the semiconductor elements and for dissipation of the heat generated in the semiconductor elements, whereby the metallic body or bodies are designed in such a way that the metallic body or bodies simultaneously serve as carriers for the semiconductor elements, and the chips are fastened to the metallic body or bodies, and wherein

- the semiconductor elements comprise first semiconductor elements which are switched in parallel,

- the body or bodies include a first body to which the chips of the first semiconductor element are fastened,

- at least a first metallic bus body is provided as a terminal for a control module,

- the control connections of the first semiconductor elements are electrically connected to the first bus body with the aid of bond wires,

- the semiconductor elements include second semiconductor elements switched in parallel,

- the body or bodies include a second body to which the chips of the second semiconductor element are fastened and which is arranged next to the first body,

- a second metallic bus body is provided as a terminal for the control module,
and

- the control terminals of the second semiconductor elements are connected to the second bus body with the aid of bond wires.

2. (Original) Circuit arrangement in accordance with Claim 1, wherein

- the semiconductor elements are electrically connected to the body or bodies so that the chips of the semiconductor elements are fastened directly without a chip housing to the body or bodies.

3. (Original) Circuit arrangement in accordance with Claim 1, wherein

- the chips of the semiconductor elements are connected to the associated body in each case by conductive adhesive or by solder.

4. (Original) Circuit arrangement in accordance with Claim 1, wherein

- to dissipate the heat generated in the semiconductor elements the body or bodies is or are arranged on a cooling device electrically isolated from the body or bodies.

5. (Original) Circuit arrangement in accordance with Claim 1, wherein

- a third metallic bus body is provided as a ground connection, and
- the terminals of the semiconductor elements are connected to the third bus body with the aid of bond wires.

6. (Original) Circuit arrangement in accordance with Claim 1, wherein
- the body or bodies and/or the first bus body and/or the second bus body and/or the third bus body are substantially made of copper.
7. (Original) Circuit arrangement comprising:
- a plurality of semiconductor elements,
 - at least one metallic body for electrical contacting of the semiconductor elements and for dissipation of the heat generated in the semiconductor elements, whereby the metallic body or bodies are designed in such a way that the metallic body or bodies simultaneously serve as carriers for the semiconductor elements, and the semiconductor elements are fastened to the metallic body or bodies,
 - first semiconductor elements of the semiconductor elements which are switched in parallel,
 - a first body of the at least one metallic body to which the first semiconductor elements are fastened,
 - at least a first metallic bus body as a terminal for a control module,
 - control connections of the first semiconductor elements which are electrically connected to the first bus body by means of bond wires,
 - second semiconductor elements of the semiconductor elements which are switched in parallel,
 - a second body of the at least one metallic body to which the second semiconductor elements are fastened and which is arranged next to the first body,

- a second metallic bus body as a terminal for the control module, and
- control terminals of the second semiconductor elements which are connected to the second bus body by means of bond wires.

8. (Original) Circuit arrangement in accordance with Claim 7, wherein

- the semiconductor elements are electrically connected to the body or bodies such that the semiconductor elements are fastened directly without housing to the body or bodies.

9. (Original) Circuit arrangement in accordance with Claim 7, wherein

- the semiconductor elements are connected to the associated body in each case by conductive adhesive or by solder.

10. (Original) Circuit arrangement in accordance with Claim 7, wherein

- to dissipate the heat generated in the semiconductor elements, the body or bodies is or are arranged on a cooling device electrically isolated from the body or bodies.

11. (Original) Circuit arrangement in accordance with Claim 7, wherein

- a third metallic bus body is provided as a ground connection, and
- at least a terminal of the semiconductor elements is connected to the third bus body with the aid of a bond wire.

12. (Original) Circuit arrangement in accordance with Claim 7, wherein
- the body or bodies and/or the first bus body and/or the second bus body and/or the third bus body are substantially made of copper.

13. - 17. **(Canceled)**